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Subject: Shelf Life Confirmation Letter

Non-hermetic (Valid for plastic encapsulated electronic) electronic packaged devices require appropriate handling to ensure optimum board performances. Melexis' Soldering Recommendations can be found on following link: <https://www.melexis.com/en/quality-environment/soldering>.

To ensure optimum board performances, moisture loading and shelf life are important parameters.

- Besides handful exceptions, our devices are qualified, against either MSL1 or MSL3 moisture sensitivity level as per J-STD-020.
- Shelf life of MSL1 devices is limited by solderability. Melexis guarantees 2 years solderability post-delivery (up to 4 years versus the data code). Note that storage period can be extended through adequate solderability tests [1] [2].
- Shelf life of MSL3 devices is limited by solderability and hermeticity of dry lock [1].
 - Dry pack hermiticity can be verified through the humidity card included into the reels. Silica gel is included to absorb any residual moisture.
 - Melexis guarantees 2 year solderability post delivery (up to 4 years versus the data code). Note that storage period can be extended through adequate solderability tests and adequate storage conditions [1] [2].
- Summary table:

MSL1			MSL3		
	Shelf life			Shelf life	
	<4years post date code	>4years post date code		<4years post date code	>4years post date code
Dry Pack Condition	Compliant	Solderability check to be conducted prior board mounting	HIC OK (Blue)	Compliant	Solderability check to be conducted prior board mounting
			HIC NOK (Pink)	Re-bake component as per JEDEC-033	Re-bake component as per JEDEC-033 Solderability check to be conducted prior board mounting

[1]: General guideline about Handling of Moisture Sensitive Devices, please refer to J-STD-033.

[2]: General guideline about Long-Term storage, please refer to JEP-160.